

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of Rule 53(b) Divisional:      Group Art Unit: 1775 (Parent)  
**MORIIZUMI, Kiyokazu et al.**

Serial No.: 09/705,897 (Parent)      Examiner: C. LAM (Parent)

Filed: February 18, 2004      Confirmation No.: 7597 (Parent)

For: **MOUNTED CIRCUIT SUBSTRATE AND METHOD FOR  
FABRICATING THE SAME FOR SURFACE LAYER  
PADS THAT CAN WITHSTAND PAD EROSION BY  
MOLTEN SOLDER APPLIED OVER A PLURALITY OF  
TIMES**

Attorney Docket No.: 001480A  
Customer Number: 38834

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

February 24, 2004

Sir:

Prior to calculation of the filing fee and examination of this application, please amend  
the above-identified application as follows:

**Amendments to the Specification** begin on page 2 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page  
3 of this paper.

**Remarks/Arguments** begin on page 6 of this paper